

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Eugene P. Marsh

Group Art Unit: 2823

Serial No.: 09/812,157

Examiner: J. Maldonado

Filed: 19 March 2001

Docket No.: 150,009,301,02

Confirmation No.: 2941

Title: METHODS FOR PATTERNING METAL LAYERS FOR USE WITH FORMING SEMICONDUCTOR DEVICES

Assistant Commissioner for Patents
Washington, D.C. 20231

We are transmitting the following documents along with this Transmittal Sheet (which is submitted in triplicate):

- ☒ An itemized return postcard.
☐ A check in the amount of \$____, for ____.
☐ A certified copy of a __ application, Serial No. __, filed _____, the right of priority of which is claimed under 35 U.S.C. §119.
☒ Other: Amendment and Response including Appendix A (18 pgs).
Amendment ____ No Additional fee is required. ____ The fee has been calculated as shown:

Fee Calculation for Claims Pending After Amendment					
	Pending Claims after Amendment (1)	Claims Paid for Earlier (2)	Number of Additional Claims (1-2)	Cost per Additional Claim	Additional Fees Required
Total Claims				x \$18 =	
Independent Claims				x \$84 =	
One or More New Multiple Dependent Claims Presented? If Yes, Add \$280 Here →					
Total Additional Claim Fees Required					

Please consider this a PETITION FOR EXTENSION OF TIME for a sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 13-4895. Triplicate copies of this sheet are enclosed.

MUETING, RAASCH & GEBHARDT, P.A.
Customer Number: 26813



26813

PATENT TRADEMARK OFFICE

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CERTIFICATE UNDER 37 CFR §1.10:

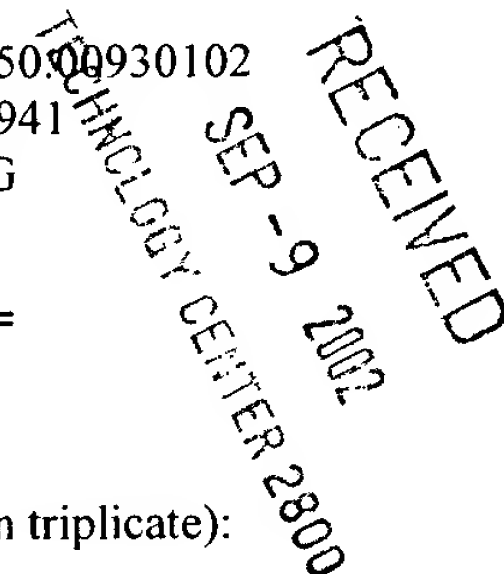
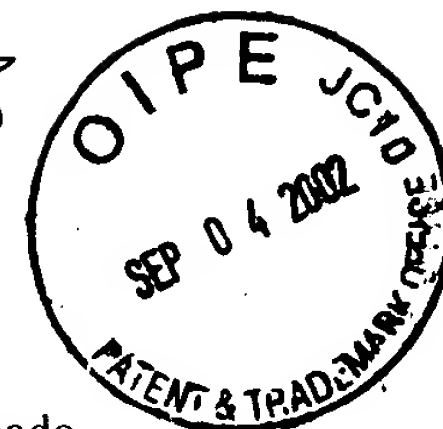
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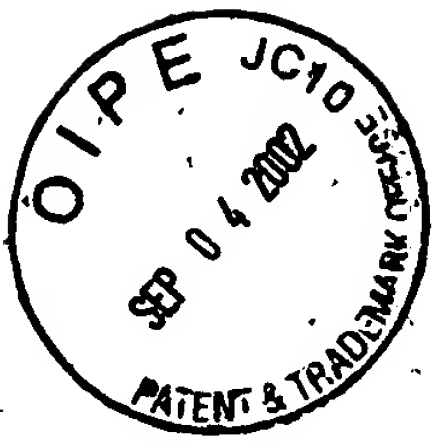
Date of Deposit: September 4, 2002

I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR §1.10 on the date indicated above and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

By: Sara E. Olson
Name: SARA E. OLSON

(LARGE ENTITY TRANSMITTAL UNDER RULE 1.10)





Docket No. 15600930102

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Eugene P. Marsh) Group Art Unit: 2823
Serial No.: 09/812,157) Examiner: J. Maldonado
Confirmation No.: 2941)
Filed: March 19, 2001)
For: METHODS FOR PATTERNING METAL LAYERS FOR USE WITH FORMING SEMICONDUCTOR DEVICES

AMENDMENT AND RESPONSE

Assistant Commissioner for Patents
Washington D.C. 20231

Dear Sir:

In response to the Office Action of June 4, 2002, please amend the above-identified application as follows:

In the Specification

Please amend the Abstract beginning at page 37, line 6, as shown below. Pursuant to 37 C.F.R. §1.121, this paragraph is also shown in Appendix A with notations to indicate the changes made.

B1
-- The present invention provides a method for forming a discontinuous conductive layer in the fabrication of integrated circuits. The method includes providing a substrate assembly having a surface including at least one metal-containing adhesion region separated by at least one surface region of the substrate assembly. A conductive metal layer is formed on the surface of the substrate assembly. The substrate assembly including the conductive metal layer thereon is then annealed. Any nonadhered conductive metal is removed from the at least one exposed surface region to form a discontinuous conductive metal layer on at least one metal-containing adhesion region, for example, by simply rinsing the substrate assembly in water. The conductive metal layer can be platinum or ruthenium. --